



Product Change Notification: MAAN-07EFLR152

Date:

19-Jan-2026

Product Category:

Interface- Controller Area Network (CAN)

Notification Subject:

CCB 7909 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for selected MCP2542FD, MCP2542WFD, MCP2544FD, MCP2544WFD, MCP2557FD, MCP2558FD, MCP2561, MCP2561FD, MCP2562 and MCP2562FD device families available in 8L SOIC (.150in) package.

Affected CPNs:

[MAAN-07EFLR152_Affected_CPN_01192026.pdf](#)

[MAAN-07EFLR152_Affected_CPN_01192026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for selected MCP2542FD, MCP2542WFD, MCP2544FD, MCP2544WFD, MCP2557FD, MCP2558FD, MCP2561, MCP2561FD, MCP2562 and MCP2562FD device families available in 8L SOIC (.150in) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No

Wire Material	Au	CuPdAu	Yes	
Die Attach Material	8390A (PFAS Free)	QMI519 (PFAS Free)	Yes	
Molding Compound Material	G600V	G600V	No	
Lead-Frame Material	CDA194	CDA194	No	
DAP Surface Prep	Ag spot	Ag on one corner	Ag on one corner	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach to standardize the use of PFAS free material at MTAI assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: May 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: January 16, 2026: Issued initial notification.

January 19, 2026: Re-issued initial notification to update notification subject.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[**PCN_MAAN-07EFLR152_Pre_and_Post Change_Summary.pdf**](#)

[**PCN_MAAN-07EFLR152_Qual Plan.pdf**](#)

Please contact your local [**Microchip sales office**](#) with questions or concerns regarding this notification.

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